



**ALPHA & OMEGA**  
SEMICONDUCTOR

**AO3442**

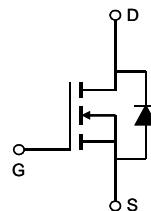
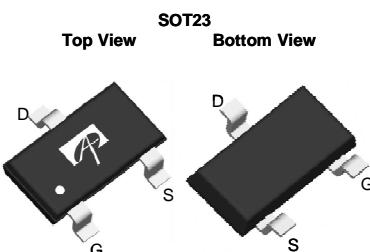
**100V N-Channel MOSFET**

### General Description

The AO3442 combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

### Product Summary

$V_{DS}$	100V
$I_D$ (at $V_{GS}=10V$ )	1A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	< 630mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	< 720mΩ



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	1	A
$T_A=70^\circ C$		0.8	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	4	
Power Dissipation <sup>B</sup>	$P_D$	1.4	W
$T_A=70^\circ C$		0.9	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup> $t \leq 10s$	$R_{\theta JA}$	70	90	°C/W
Maximum Junction-to-Ambient <sup>A,D</sup> Steady-State		100	125	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	63	80	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	100			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			$\pm100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.7	2.3	2.9	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	4			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=1\text{A}$ $T_J=125^\circ\text{C}$	514	630		$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=0.8\text{A}$	983	1200		
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=1\text{A}$		2.8		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.9	1.2	V
$I_S$	Maximum Body-Diode Continuous Current <sup>G</sup>				1	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=50\text{V}, f=1\text{MHz}$		100		pF
$C_{\text{oss}}$	Output Capacitance			13		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			5		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	2.5	5	7.5	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=50\text{V}, I_D=1\text{A}$		2.8	6	nC
$Q_g(4.5\text{V})$	Total Gate Charge			1.5	3	nC
$Q_{\text{gs}}$	Gate Source Charge			0.4		nC
$Q_{\text{gd}}$	Gate Drain Charge			0.8		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=50\text{V}, R_L=50\Omega, R_{\text{GEN}}=3\Omega$		5		ns
$t_r$	Turn-On Rise Time			4		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			12		ns
$t_f$	Turn-Off Fall Time			5		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=5.6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		52		ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=5.6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		60		nC

A. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using  $\leqslant 10\text{s}$  junction-to-ambient thermal resistance.

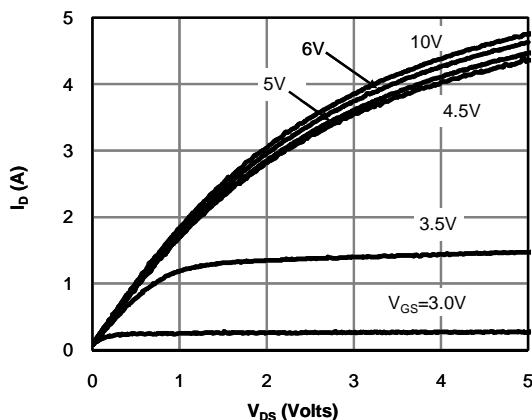
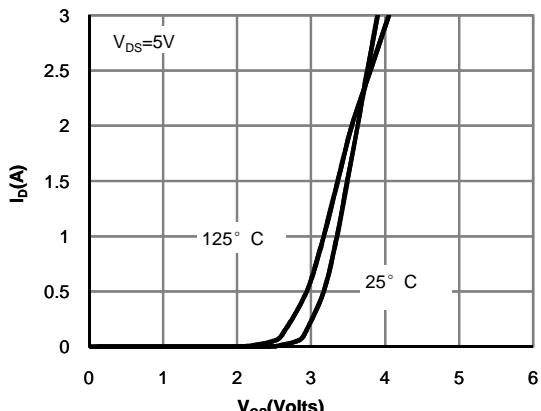
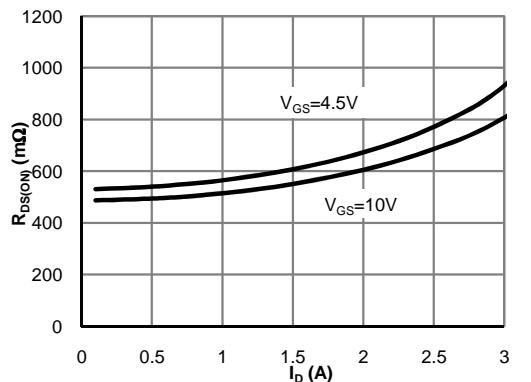
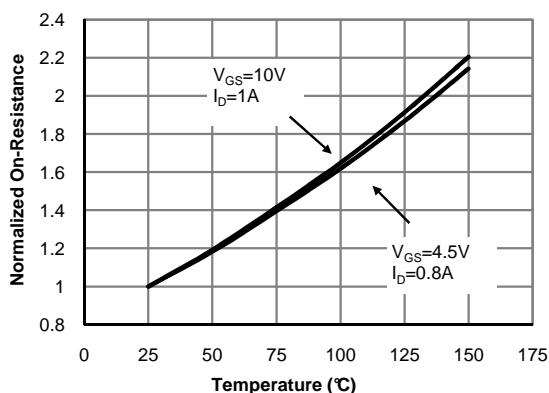
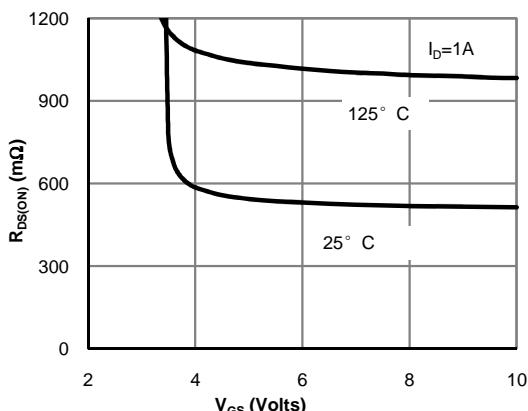
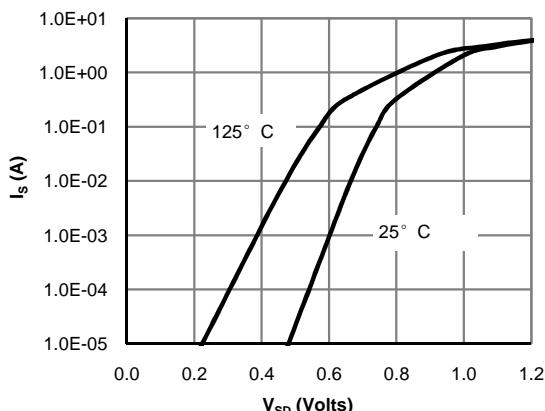
C. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

D. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using  $<300\mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

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**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Fig 1: On-Region Characteristics (Note E)**

**Figure 2: Transfer Characteristics (Note E)**

**Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)**

**Figure 4: On-Resistance vs. Junction Temperature (Note E)**

**Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)**

**Figure 6: Body-Diode Characteristics (Note E)**

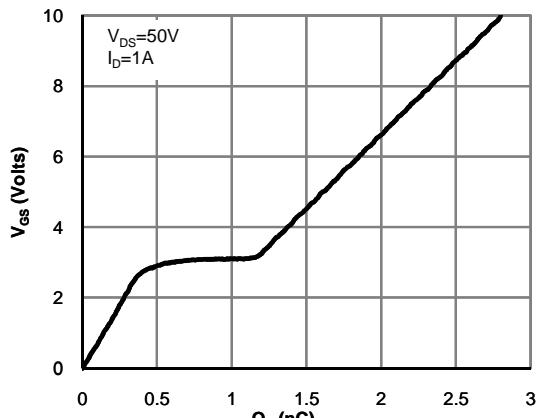
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


Figure 7: Gate-Charge Characteristics

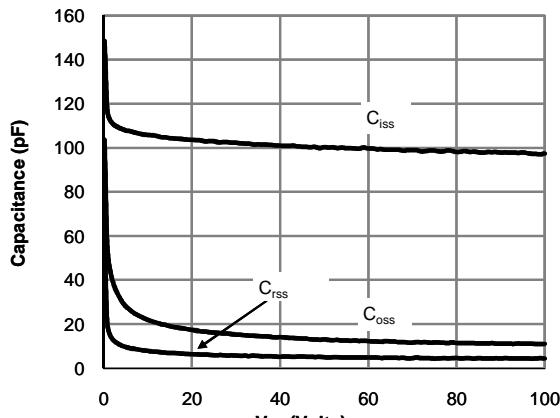


Figure 8: Capacitance Characteristics

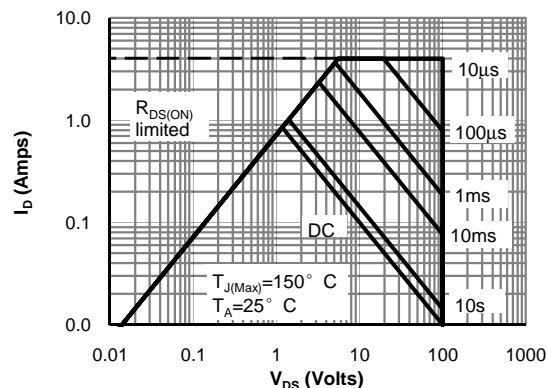
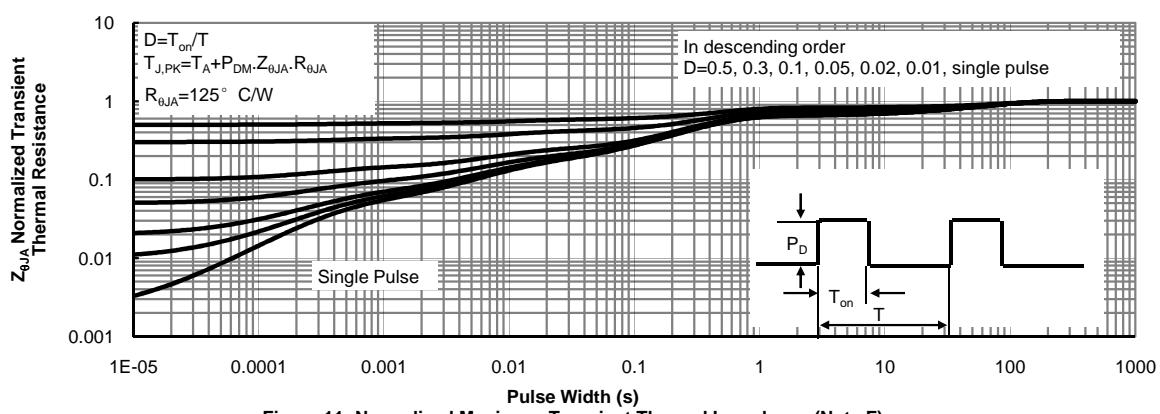
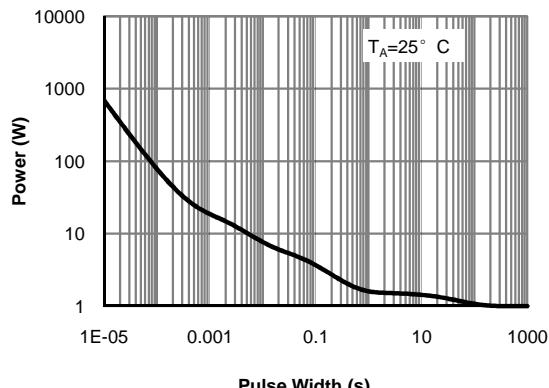
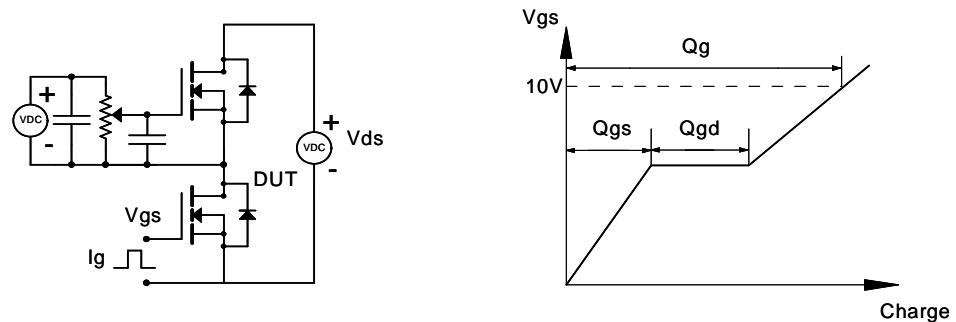
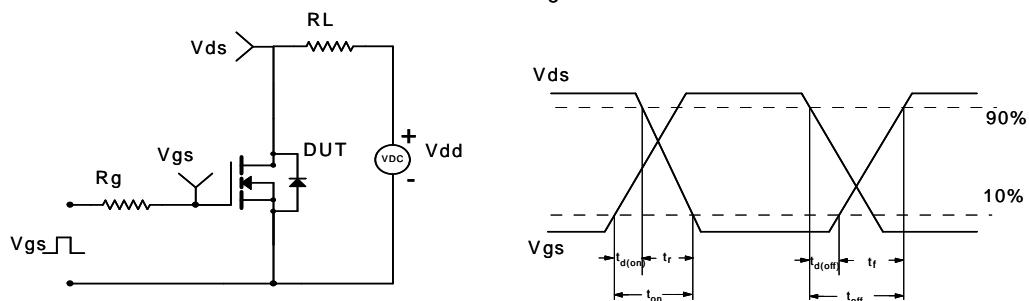
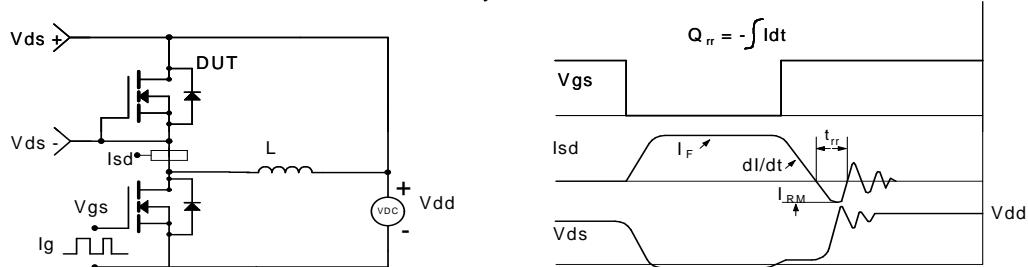


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)



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